

Description

The 25N06 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO252-2L

General Features

 $V_{DS} = 60V I_{D} = 25 A$

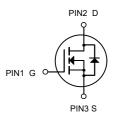
 $R_{DS(ON)} < 30 m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
25N06	TO252-2L	25N06XXXX YYYY	2500

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter Rating		Units	
V _D s	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	ous Drain Current, V _{GS} @ 10V ¹ 25		
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	DV ¹ 15		
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	tinuous Drain Current, V _{GS} @ 10V ¹ 5.6		
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	10V ¹ 4.5		
IDM	Pulsed Drain Current ²	Pulsed Drain Current ² 46		
EAS	Single Pulse Avalanche Energy ³	Single Pulse Avalanche Energy ³ 25.5		
las	Avalanche Current	22.6		
P _D @T _C =25°C	Total Power Dissipation ⁴	Total Power Dissipation ⁴ 34.7		
P _D @T _A =25°C	Total Power Dissipation ⁴	Total Power Dissipation ⁴ 2		
Тѕтс	Storage Temperature Range	Storage Temperature Range -55 to 150		
TJ	Operating Junction Temperature Range	rature Range -55 to 150		



R _θ JA	Thermal Resistance Junction-Ambient ¹	62	°C/W
Rejc	Thermal Resistance Junction-Case ¹	3.6	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
△BVbss/△TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.063		V/°C
	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =15A		24	30	
Rds(on)		V _{GS} =4.5V , I _D =10A		32	40	mΩ
V _G S(th)	Gate Threshold Voltage	V V 1 050 A	1.2		2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	—V _{GS} =V _{DS} , I _D =250uA		-5.24		mV/°C
		V _{DS} =48V , V _{GS} =0V , T _J =25°C			1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		17		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.2		Ω
Qg	Total Gate Charge (4.5V)			12.6		
Q _{gs}	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =12A		3.2		nC
Q _{gd}	Gate-Drain Charge			6.3		
Td(on)	Turn-On Delay Time			8		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		14.2		
T _d (off)	Turn-Off Delay Time	R _G =3.3 , I _D =10A		24.4		ns
T _f	Fall Time	10-10A		4.6		
Ciss	Input Capacitance			1378		
Coss	Output Capacitance			86		pF
Crss	Reverse Transfer Capacitance			64		-
ls	Continuous Source Current ^{1,5}				23	Α
Іѕм	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			46	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

Note:

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=22.6A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



Typical Characteristics

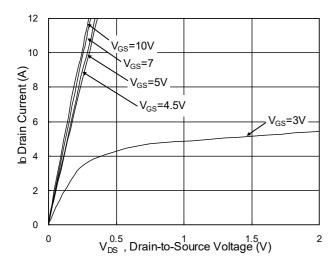


Fig.1 Typical Output Characteristics

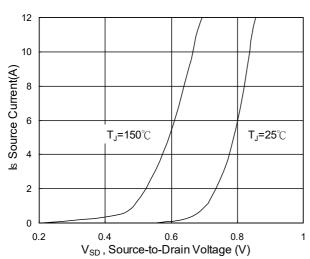


Fig.3 Forward Characteristics of Reverse

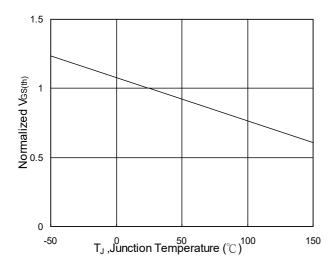


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

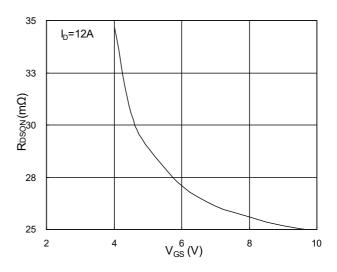


Fig.2 On-Resistance v.s Gate-Source

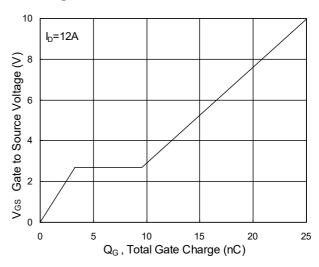


Fig.4 Gate-Charge Characteristics

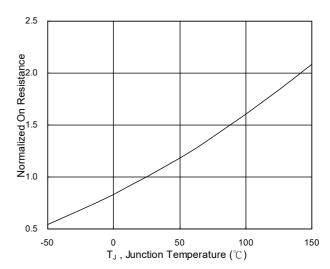
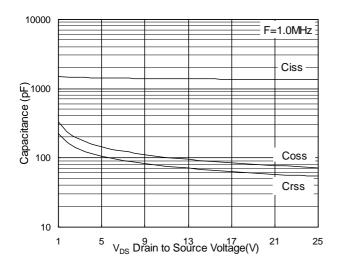


Fig.6 Normalized R_{DSON} v.s T_J



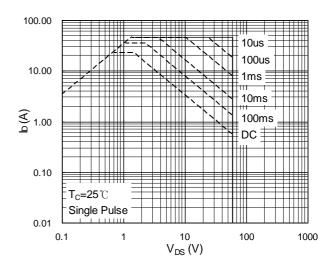


Fig.7 Capacitance

Fig.8 Safe Operating Area

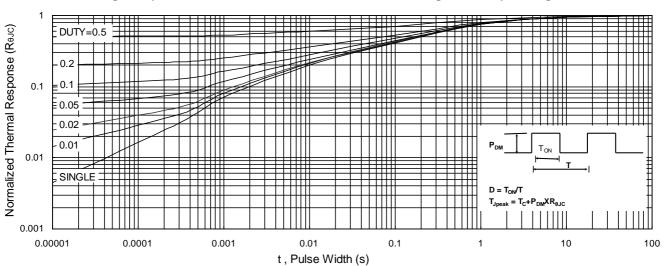


Fig.9 Normalized Maximum Transient Thermal Impedance

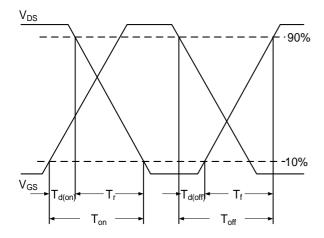


Fig.10 Switching Time Waveform

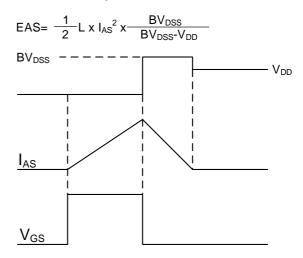
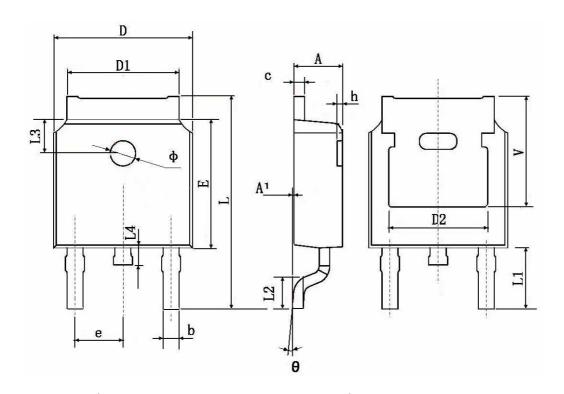


Fig.11 Unclamped Inductive Waveform



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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